Steam aging chamber ETSP- STH series



Product Intro

Steam aging chamber is designed for artificial aging of all electronic components and circuit boards. This includ es high density discrete components, relays, transistors, capacitors, SMT, and axial components. Artificial steam aging of components must occur over a very narrow te mperature range, typically at 93 C +/- 5 degrees. ETSP-S TH series are the only systems currently on the market that meet this precise control requirement. This thermal accuracy makes ETSP-STH series ideal for component m anufacturers and military, commercial, and industrial en d users.

Technical Features

Temperature range	RT ~ 99 °C
Temperature stability	Less than ± 0.5 °C